Product Change Notification

107483 - 00

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com

Product Change Notification

Change Notification #:	**107483 - 00**
Change Title:	**Intel® Optical Transceiver, TXN181070850, PCN 107483-00, Product Design, Product Material, PCB and Optics Vendor Related Changes, and Product Label Changes**
Date of Publication:	**April 19, 2007**

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date of Samples Availability:	Apr 19, 2007
Date of Qualification Data Availability:	May 04, 2007
Date Customer Must be Ready to Receive Post-Conversion Material:	May 19, 2007
Date of First Availability of Post-Conversion Material:	May 19, 2007

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

PCB Vendor Change

The Intel® TXN181070850 Optical Transceiver uses Streamline Circuits Printed Circuit Board (PCB). Intel qualified a new PCB vendor. The Intel® TXN181070850 Optical Transceiver will use Multek Printed Circuit Board (PCB).

Optics Vendor Related Changes

The Intel® TXN181070850 Optical Transceiver uses Advanced Optical Components (AOC) Transmitter Optical Sub-Assembly (TOSA), and AOC Receiver Optical Sub-Assembly (ROSA). AOC is implementing a few changes on the TOSA and ROSA used for TXN181070850. The changes are described in detail below.

TOSA

1. Header Glass and Pins: AOC will change the high speed glass used in the header to brown glass to improve reliability. AOC will also change two small pins in the header to have nail heads, giving a much larger area to wirebond.

2. VCSEL: AOC will add a passivation layer to VCSEL and change the minimum VCSEL resistance from 43 ohms to 41ohms. AOC will change the site for VCSEL manufacturing and for TOSA connectorization process.
3. TO Can: AOC will change the TO can from tapered wall to straight (cylindrical) wall to eliminate mechanical shift in barrel.
4. Gold pads: AOC will increase the gold pad size on the ceramic spacer to allow more room for die attach and wirebond.
5. Site Change: AOC will move TOSA connectorizing and testing from Allen, Texas to Fabrinet, Thailand to improve supply. Epitaxial fabrication operation will be moved from Richardson, TX to Allen, TX.

ROSA

1. Header Glass and Pins: AOC will change the high speed glass used in the header to brown glass to improve reliability. AOC will also change two small pins in the header to nail heads which gives a much larger area to wirebond.
2. Transimpedance Amplifier (TIA): AOC will change the TIA from Gennum 1052 TIA to Gennum 1052-A2A. The Gennum 1052-A2A incorporates an inductor value change in the receiver circuit which improves consistency of eye cross-point.
3. Site Change: AOC will move ROSA connectorizing and testing from Allen, Texas to Fabrinet, Thailand to improve supply. Epitaxial fabrication operation will be moved from Richardson, TX to Allen, TX.
4. AOC will add a second source barrel supplier.

Label Changes
Packaging and device labels will have the appropriate RoHS Compliance logos for China, US, and Europe.

Customer Impact of Change and Recommended Action:

Intel has performed full quality and reliability including 1000 hours testing and complete design verification testing for TXN181070850 to ensure that there is no quality, reliability or functional implications to our customers. The qualification reports for TXN181070850 will be available on May 4, 2007. Please contact your local Intel sales representative to request the qualification reports.
First samples of the TXN181070850 with PCB and optics vendor related changes are available now. General production availability for the TXN181070850 with PCB and optics vendor related changes will be in May 2007.

Intel will change the Product Code and MM# for TXN181070850 with PCB and optics vendor related changes.

Products Affected / Intel Ordering Codes:

Affected Product Code	Affected MM#	New Product Code	New MM#
TXN181070850X28	870071	TXN181070850X48	885973
TXN181070850X2D	870073	TXN181070850X4D	887706
TXN181070850X2L	875867	TXN181070850X4L	890359
TXN181070850X2N	884238	TXN181070850X4N	890316
TXN181070850X2P	890437	TXN181070850X4P	890360

Reference Documents / Attachments:

Document:	Location #:
Qual Data	Please Contact your Local Intel Field Sales Representative

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
April 19, 2007	00	Originally Published PCN